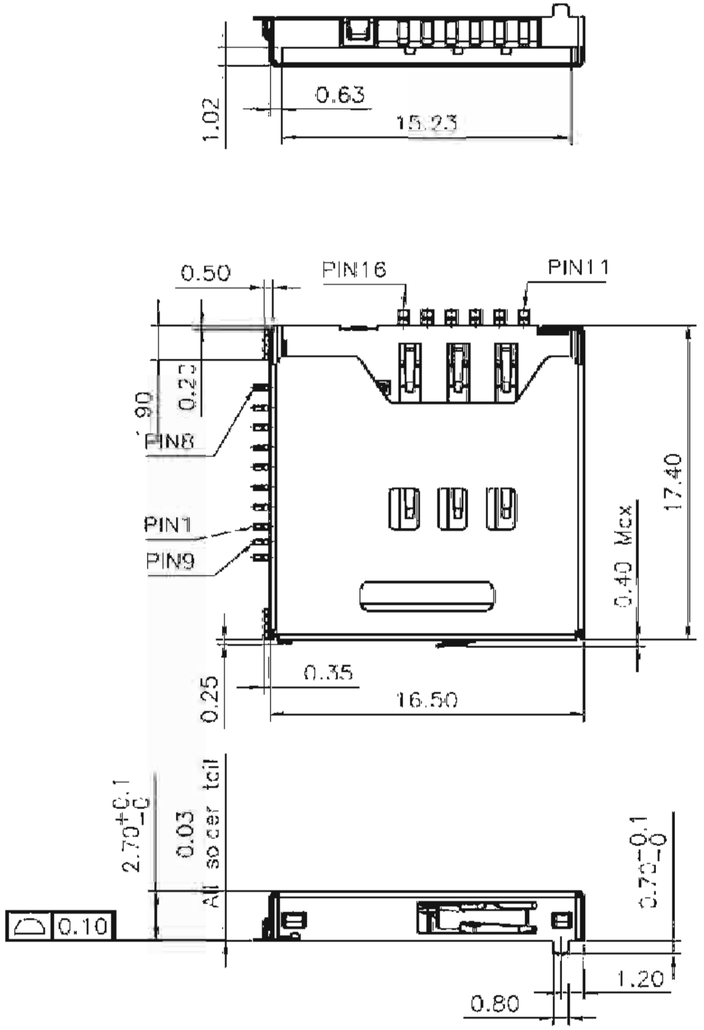
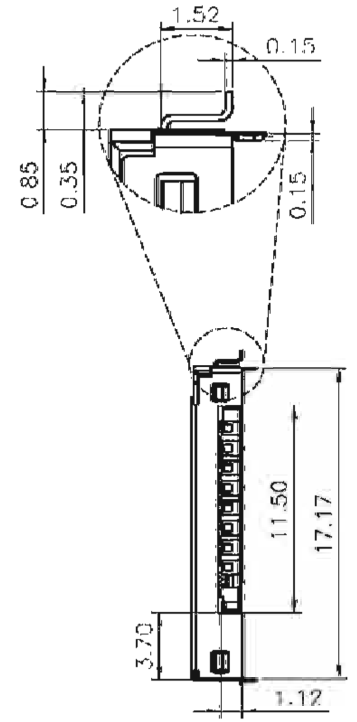
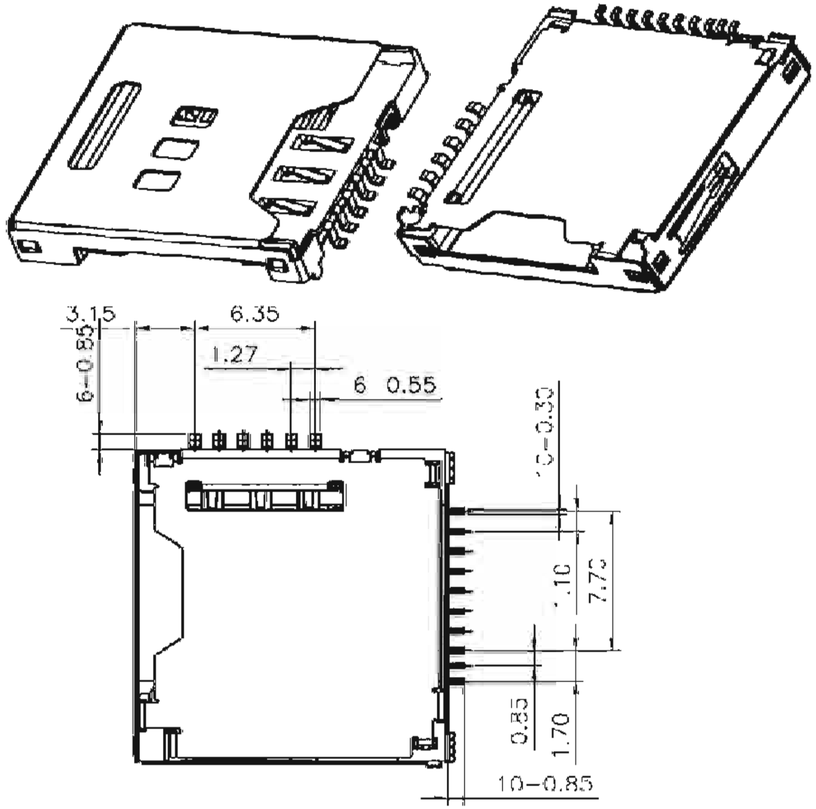






112G-T X 0 0-R
1 2 3

1.Type

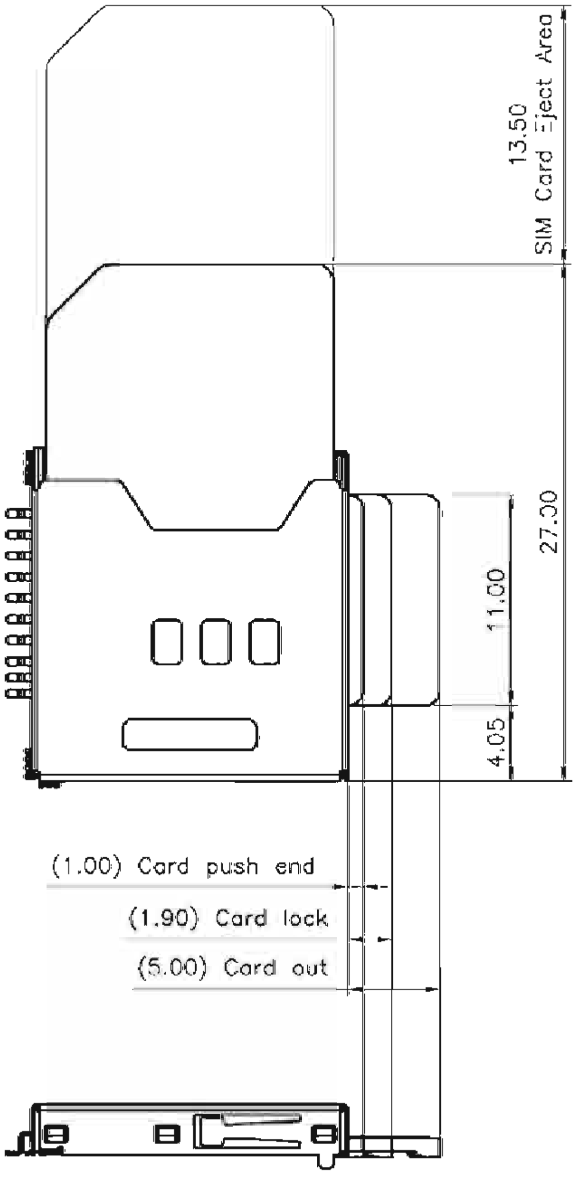
T: Top Mount

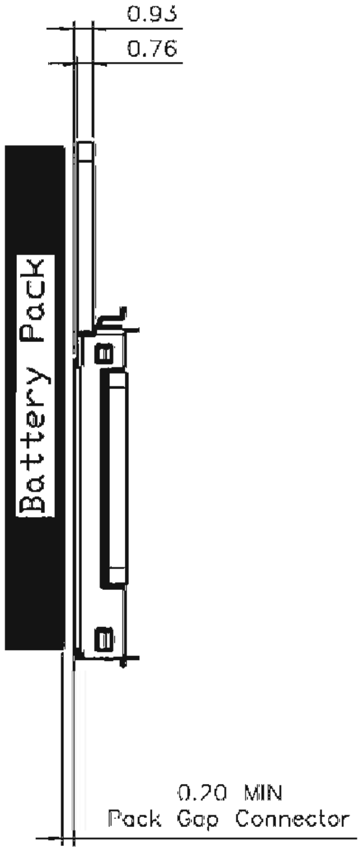
2.Contact Plating

A: 15u"gold plating

B: 3u"gold plating

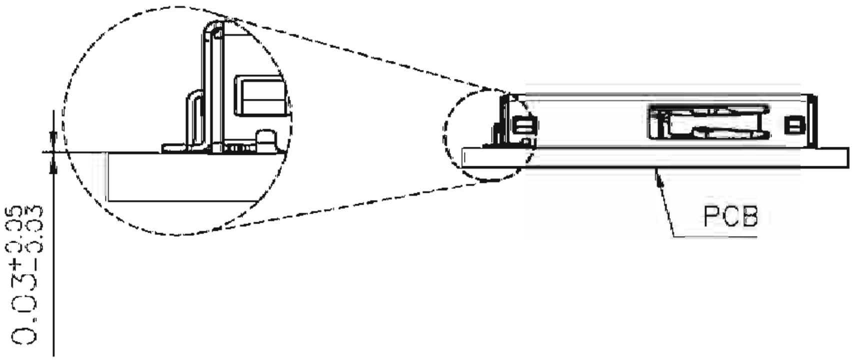
3.RoHS

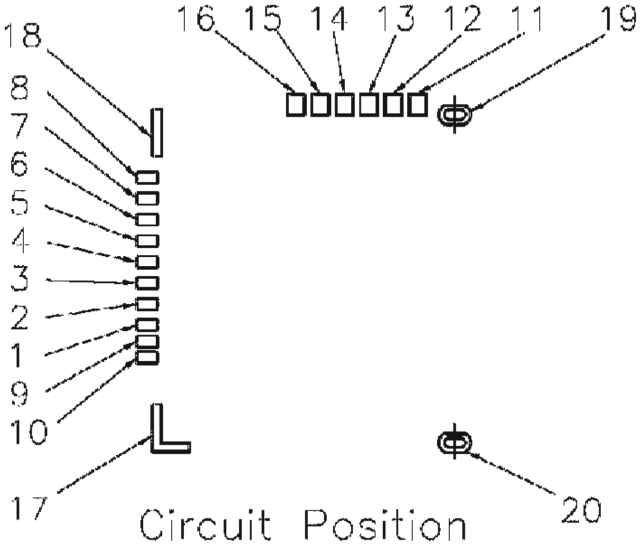




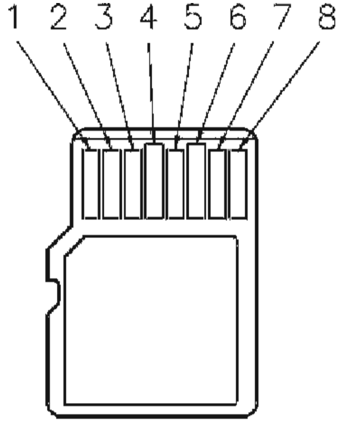
1. MATERIAL :
   INSULATOR BODY : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.
   EJECTOR: HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.
   SHELL: STAINLESS STEEL
   Micro SD CARD CONTACT : COPPER ALLOY
   Micro SD CARD DETECT TERMINAL: COPPER ALLOY
   SIM CARD CONTACT : COPPER ALLOY
   COIL SPRING : STAINLESS STEEL
   CRANK AXLE : STAINLESS STEEL
2. PLATING :
   Micro SD CARD CONTACT: Au ON CONTACT AREA,
   Sn ON SOLDER TAIL AREA
   SIM CARD CONTACT: Au ON Contact AREA
   DETECT&GROUND PIN : Au ON CONTACT AREA,

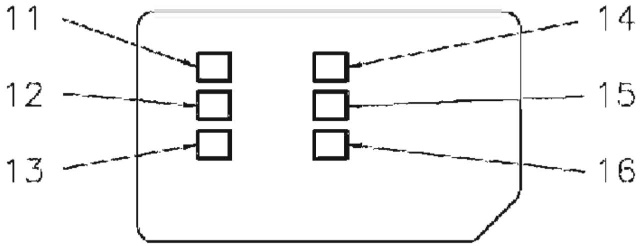
   BOTTOM COVER : BASE PLATING 40u"min Ni OVER ALL,
   1u"min.Au ON SOLDER AREA

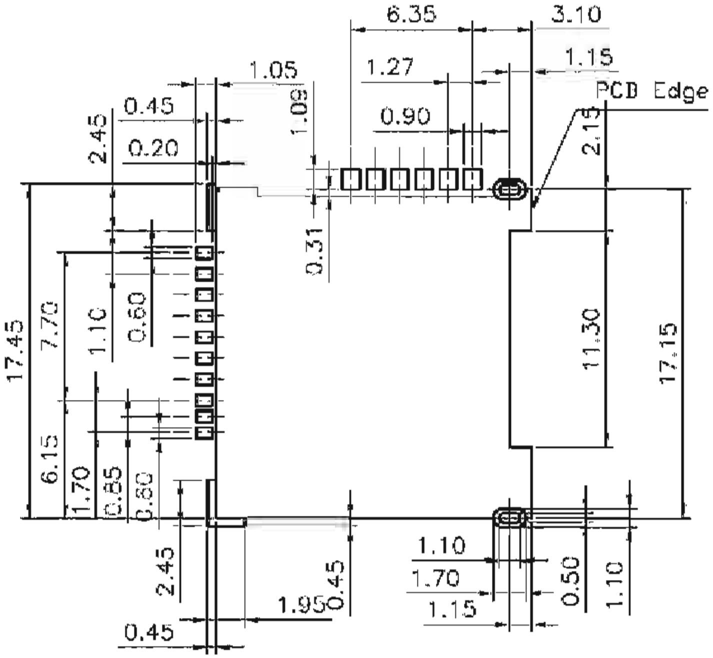




Circuit Position







Recommended PCB Layout

MicroSD Card			
Pin NO.	Name	Type	Description
1	DAT2	I/O/PP	Date Line (bit2)
2	CD/DAT3	I/O/PP	Card Detect Date Line (bit2)
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Date Line (bit0)
8	DAT1	I/O/PP	Date Line (bit1)
9	---		Detect Pin
10	---	---	Ground Pin
SIM Card			
11	VCC		
12	RST		
13	CLK		
14	CND		
15	VPP		
16	I/O		
GROUND			
17~20	---	---	Ground Pin